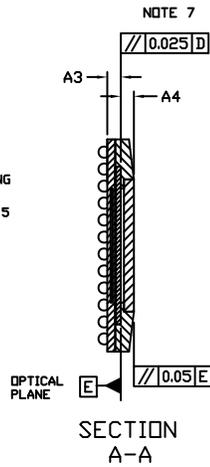
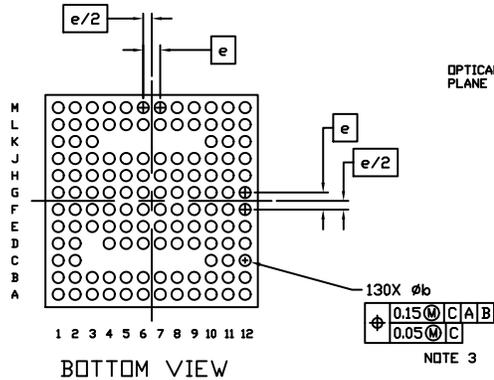
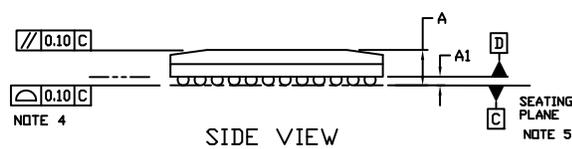
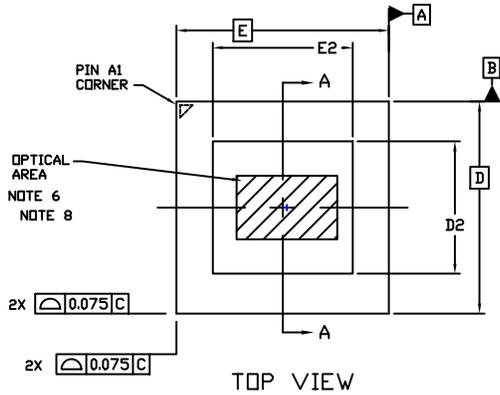
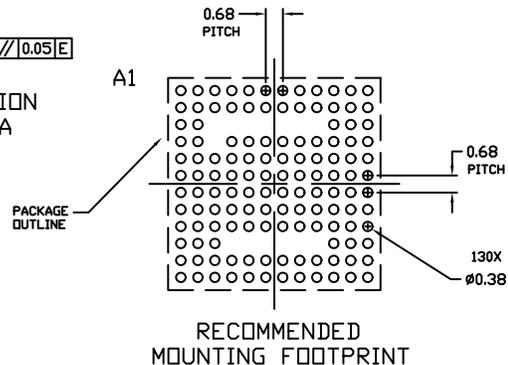


IBGA130 8.5x8.5
CASE 503BK
ISSUE B

DATE 23 MAY 2017



DIM	MILLIMETERS	
	MIN.	MAX.
A	---	1.57
A1	0.30	0.40
A3	0.495	0.595
A4	0.475	0.575
b	0.40	0.50
D	8.50 BSC	
D2	5.20	5.40
E	8.50 BSC	
E2	5.50	5.70
e	0.68 BSC	



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO D AND E WILL BE 1°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATA SHEET FOR TOTAL ARRAY AND FIRST ACTIVE PIXEL DEFINITIONS.
7. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.
8. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X=166 MICRONS, Y=0 MICRONS ±75 MICRONS.

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